

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
25 August 2005 (25.08.2005)

PCT

(10) International Publication Number  
**WO 2005/077602 A1**

(51) International Patent Classification<sup>7</sup>: **B24D 11/00**

(21) International Application Number:  
PCT/KR2005/000441

(22) International Filing Date: 16 February 2005 (16.02.2005)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:  
10-2004-0010492

17 February 2004 (17.02.2004) KR

10-2004-0016402 11 March 2004 (11.03.2004) KR

(71) Applicant (for all designated States except US): **SKC CO., LTD.** [KR/KR]; 633 Jeongja-1-dong Jangan-gu Suwon, Kyungki-do 440-745 (KR).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **SONG, Eu-Gene** [KR/KR]; 301-19 Sachang-dong Heungduk-gu, Cheongjoo Choongchungbook-do, 361-833 (KR). **LEE, Ju-Yeol** [KR/KR]; 101-1402 Donga Apt. Jeongja-dong, Bundang-gu Sungnam, Kyungki-do, 463-010 (KR). **KIM,**

**Sung-Min** [KR/KR]; 304-202 Joogong Apt. Gaesin-dong, Heungduk-gu Cheongjoo, Choongchungbook-do, 361-804 (KR). **KIM, Jae-Seok** [KR/KR]; 307-1305 Joogong Apt. Boonpyung-dong, Heungduk-gu Cheongjoo, Choongchungbook-do, 361-767 (KR). **LEE, Hyun-Woo** [KR/KR]; 766 Soogok-dong Heungduk-gu, Cheongjoo Choongchungbook-do, 361-150 (KR).

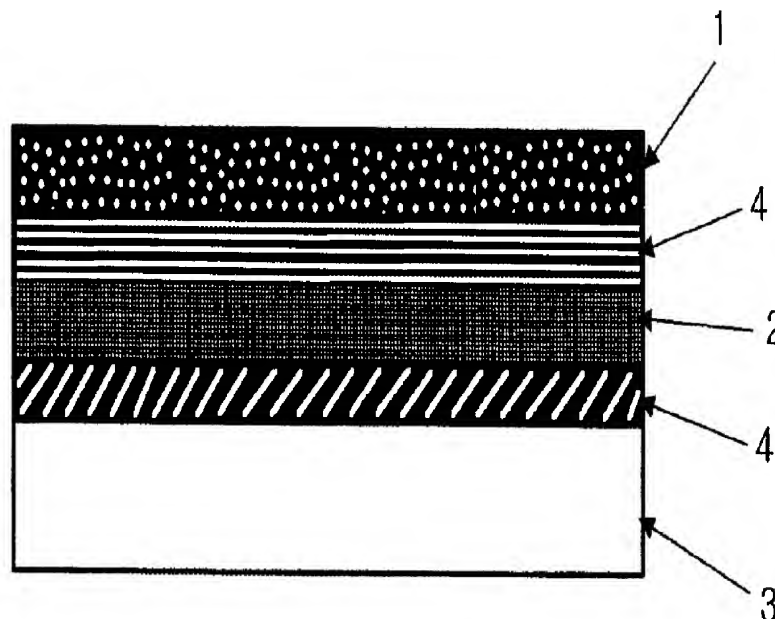
(74) Agent: **C & S PATENT AND LAW OFFICE**; C-2306 Daelim Acrotel, 467-6 Dogok-dong Kangnam-gu Seoul, 135-971 (KR).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH,

[Continued on next page]

(54) Title: BASE PAD POLISHING PAD AND MULTI-LAYER PAD COMPRISING THE SAME



(57) Abstract: Disclosed is a base pad of polishing pad, which is used in conjunction with polishing slurry during a chemical-mechanical polishing or planarizing process, and a multilayer pad using the same. Since the base pad according to the present invention does not have fine pores, it is possible to prevent premeation of polishing slurry and water and to avoid nonuniformity of physical properties. Therby, it is possible to lengthen the lifetime of the polishing pad.

WO 2005/077602 A1



GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**

— with international search report

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*